PRELIMINARY PRODUCT INFORMATION

MOS FIELD EFFECT TRANSISTOR NP55N06CLD,NP55N06DLD,NP55N06ELD

SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

DESCRIPTION

EC

This product is N-Channel MOS Field Effect Transistor designed for high current switching applications.

FEATURES

- Channel Temperature 175 degree rated
- Super Low On-state Resistance $R_{DS(on)1} = 17 \text{ m}\Omega \text{ (MAX.)} (V_{GS} = 10 \text{ V}, \text{ Id} = 28 \text{ A})$ $R_{DS(on)2} = 23 \text{ m}\Omega \text{ (MAX.)} (V_{GS} = 5 \text{ V}, \text{ Id} = 28 \text{ A})$
- Low Ciss : Ciss = 1920 pF (TYP.)
- Built-in Gate protection diode

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ABSOLUTE MAXIMUM RATINGS ($T_A = 25 \ ^{\circ}C$)

Drain to Source Voltage	Vdss	60	V
Gate to Source Voltage	Vgss	±20	V
Drain Current (DC)	D(DC)	±55	А
Drain Current (Pulse) Note1	D(pulse)	±165	А
Total Power Dissipation (TA = 25 °C)	Р⊤	1.8	W
Total Power Dissipation (Tch = 25 °C)	Рт	77	W
Single Avalanche Current	AS	TBD	А
Single Avalanche Energy Note2	Eas	TBD	mJ
Channel Temperature	Tch	175	°C
Storage Temperature	Tstg	–55 to + 175	°C

Notes 1. PW \leq 10 μ s, Duty cycle \leq 1 %

2. Starting T_{ch} = 25 °C, R_G = 25 Ω , V_{GS} = 20 V \rightarrow 0

THERMAL RESISTANCE

Channel to Case	Rth(ch-C)	1.95	°C/W
Channel to Ambient	Rth(ch-A)	83.3	°C/W

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

The information contained in this document is being issued in advance of the production cycle for the device. The parameters for the device may change before final production or NEC Corporation, at its own discretion, may withdraw the device prior to its production.

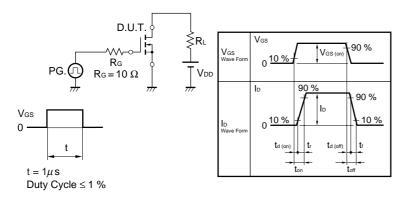
ORDERING INFORMATION

PART NUMBER	PACKAGE
NP55N06CLD	TO-220AB
NP55N06DLD	TO-262
NP55N06ELD	TO-263

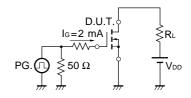
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	RDS(on)1	V _{GS} = 10 V, I _D = 28 A		13	17	mΩ
	RDS(on)2	Vgs = 5 V, Id = 28 A		17	23	mΩ
	RDS(on)3	Vgs = 4 V, Id = 28 A		20	27	mΩ
Gate to Source Cut-off Voltage	VGS(off)	$V_{DS} = 10 \text{ V}, \text{ Id} = 250 \ \mu\text{A}$	1.0	1.5	2.0	V
Forward Transfer Admittance	y _{fs}	Vds = 10 V, Id = 28 A	13	42		S
Drain Leakage Current	Ibss	Vds = 60 V, Vgs = 0 V			10	μA
Gate to Source Leakage Current	lgss	$V_{GS} = \pm 20 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$			±10	μA
Input Capacitance	Ciss	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		1920	2880	pF
Output Capacitance	Coss			380	570	pF
Reverse Transfer Capacitance	Crss			140	250	pF
Turn-on Delay Time	td(on)	$I_{D} = 28 \text{ A}, \text{ V}_{\text{GS(on)}} = 10 \text{ V}, \text{ V}_{\text{DD}} = 30 \text{ V},$		35	80	ns
Rise Time	tr	R _G = 10 Ω		440	1100	ns
Turn-off Delay Time	td(off)			110	220	ns
Fall Time	tr			230	500	ns
Total Gate Charge 1	Q G1	$I_D = 55 \text{ A}, V_{DD} = 48 \text{ V}, \text{ Vgs} = 10 \text{ V}$		44	66	nC
Total Gate Charge 2	Q _{G2}	$I_D = 55 \text{ A}, V_{DD} = 48 \text{ V}, \text{ Vgs} = 5 \text{ V}$		25	38	nC
Gate to Source Charge	QGS			8		nC
Gate to Drain Charge	Qgd			13		nC
Body Diode Forward Voltage	VF(S-D)	IF = 55 A, VGS = 0 V		1.0		V
Reverse Recovery Time	trr	IF = 55 A, VGS = 0 V, di/dt = 100 A/µs		60		ns
Reverse Recovery Charge	Qrr			100		nC

ELECTRICAL CHRACTERISTICS (TA = 25 °C)

TEST CIRCUIT 1 SWITCHING TIME

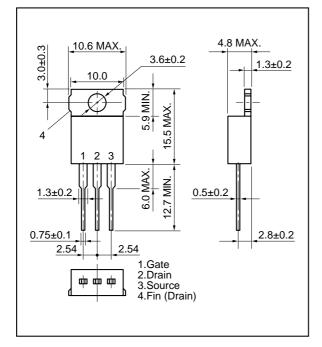


TEST CIRCUIT 2 GATE CHARGE

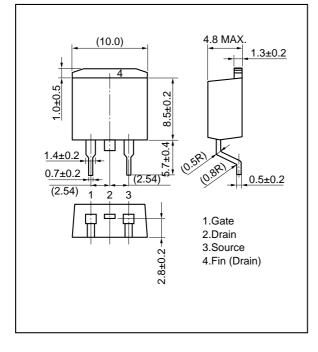


PACKAGE DRAWINGS (Unit : mm)

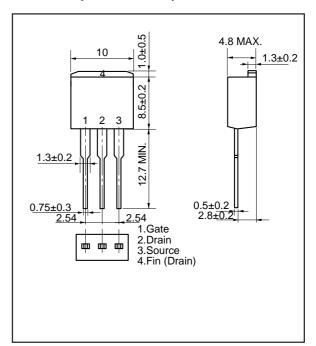
1. TO-220AB (MP-25)



3. TO-263 (JEDEC type : MP-25ZJ)



2. TO-262 (MP-25 Fin Cut)



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- Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots
- Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
- Specific: Aircrafts, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

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Anti-radioactive design is not implemented in this product.

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